PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the re-record assignment to include Assignee Altis Semiconductor previously recorded on reel previously recorded on Reel 017173 Frame 0771. Assignor(s) hereby confirms the 11/289,787.

CONVEYING PARTY DATA

Name	Execution Date
Woosik Kim	12/12/2005
Chanro Park	12/09/2005

RECEIVING PARTY DATA

Name:	Infineon Technologies AG
Street Address:	StMartin-Str. 53
City:	Munich
State/Country:	GERMANY
Postal Code:	81669

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11289787

CORRESPONDENCE DATA

Fax Number: (301)762-4056

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 301/424-3640 Email: jkw@usiplaw.com

Correspondent Name: PJF (Edell, Shapiro & Finnan)

Address Line 1: 1901 Research Blvd.

Address Line 2: Suite 400

Address Line 4: Rockville, MARYLAND 20850

ATTORNEY DOCKET NUMBER:	3001.0033C
NAME OF SUBMITTER:	Patrick J. Finnan

Total Attachments: 13

PATENT REEL: 017212 FRAME: 0362

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PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1 02/22/2006 500080043

SUBMISSION TYPE:

CORRECTIVE ASSIGNMENT

NATURE OF CONVEYANCE:

Corrective Assignment to correct the Corrective assignment to re-record assignment to include Assignee Altis Semicondcutor SNC previously recorded on Reel 017173 Frame 0771. Assignor(s) hereby confirms the 11289787.

CONVEYING PARTY DATA

Name	Execution Date
Woosik Kim	12/12/2005
Chanro Park	12/09/2005

RECEIVING PARTY DATA

Name:	Infinean Technologies AG
Street Address:	StMartin-Str. 53
City:	Munich
State/Country:	GERMANY
Postal Code:	81669

Name:	Altis Semiconductor	
Street Address:	SNC 224 Bld. John Kennedy	
Internal Address:	91105	
City:	Corbeil Essonnes Cedex	
State/Country:	FRANCE	
Postal Code:	31P	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11289787	

CORRESPONDENCE DATA

Fax Number:

(301)762-4056

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone:

301/424-3640

Email:

jkw@usiplaw.com

Correspondent Name:

PJF (Edell, Shapiro & Finnan)

PATENT

REEL: 017212 FRAME: 0364

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Address Line 1:

1901 Research Blvd.

Address Line 2:

Suite 400

Address Line 4:

Rockville, MARYLAND 20850

ATTORNEY DOCKET NUMBER:

3001.0033C

NAME OF SUBMITTER:

Patrick J. Finnan

Total Attachments: 2

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PATENT

REEL: 017212 FRAME: 0365

ASSIGNMENT

For good and valuable consideration, WE, Woosik Kim, a citizen of South Korea, residing at 24 rue du Mont aux Lievres, 77350 Boissettes, France; and Chanro Park, a citizen of South Korea, residing at 14, rue du Coin-Muzard, 77920 Samois sur Seine, France, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany; and Altis Semiconductor, a corporation organized and existing under the laws of France, having its principal place of business at SNC 224 Bld., John Kennedy, ZIP 31 P, 91105 Corbeil Essonnes Cedex, France, hereinafter "Assignees", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

Method of Forming Dual Interconnects in Manufacturing MRAM Cells

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignees may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignees, their successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignces, their successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignces, their successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignees, their successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Woosik KIM

SIGNATURE:

E: Woosik Kin 27 12. Pec. 2005 DATE:

Chanro Park

SIGNATURE:

DATE:

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Chanro Park

DATE: 12/9/2005

PATENT

REEL: 017212 FRAME: 0367

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1 02/15/2006 500078605

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Woosik Kim	12/12/2005
Chanro Park	12/09/2005

RECEIVING PARTY DATA

Name:	Infineon Technologies AG
Street Address:	StMartin-Str. 53
City:	Munich
State/Country:	GERMANY
Postal Code:	81669

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11289787

CORRESPONDENCE DATA

Fax Number: (301)762-4056

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 301/424-3640
Email: jkw@usiplaw.com

Correspondent Name: PJF (Edell, Shapiro & Finnan)

Address Line 1: 1901 Research Blvd.

Address Line 2: Suite 400

Address Line 4: Rockville, MARYLAND 20850

NAME OF SUBMITTER: Patrick J. Finnan

Total Attachments: 2

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017173/0771 PAGE 2

ASSIGNMENT SERVICES BRANCH PUBLIC RECORDS DIVISION

ASSIGNMENT

For good and valuable consideration, WE, Woosik Kim, a citizen of South Korea, residing at 24 rue du Mont aux Lievres, 77350 Boissettes, France; and Chanro Park, a citizen of South Korea, residing at 14, rue du Coin-Muzard, 77920 Samois sur Seine, France, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany; and Altis Semiconductor, a corporation organized and existing under the laws of France, having its principal place of business at SNC 224 Bld., John Kennedy, ZIP 31 P, 91105 Corbeil Essonnes Cedex, France, hereinafter "Assignees", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

Method of Forming Dual Interconnects in Manufacturing MRAM Cells

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignees may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignees, their successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignees, their successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignees, their successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignees, their successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Woosik KIM

SIGNATURE: WOOSik Kin 25

DATE: 12. Dec. 2005

Chanro Park

SIGNATURE:

DATE:

Chanro Park

SIGNATURE: Chamforthe DATE: 12/9/2001

PATENT REEL: 017212 FRAME: 0371

RECORDED: 02/24/2006